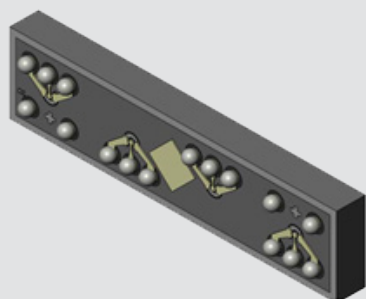


Product Brief



Key Features

- Very high reliability.
- Integrated lens.
- Enables passive alignment with suitable optical design.

118A40

1x4 56-Gbaud Substrate-Illuminated PIN Photodiode Array

Overview

118A40 is a mesa technology InGaAs/InP 1x4 PIN photodetector array that supports lightwave applications in the 56-Gbaud range over the temperature range -5°C to 85°C. The p-side layout includes metalized pads that accept automated solder-ball attachment as an enabler for flip-chip bonding. The substrate side incorporates an InP lens etched into the semi-insulating substrate surface, with single-layer dielectric AR coating. This design results in forgiving chip placement tolerances and enables passive alignment to the optical source in some optical configurations.

Qualified per the intent of Telcordia GR-468 and offering class-leading electrical and optical performance, the chip is also qualified for use in nonhermetic environments.

Contact Broadcom for additional detailed information about these products for your application.

Ordering Information

Product Code	Description
118A40	1x4 56-Gb/s substrate-illuminated, lensed PIN detector chip array